Cypress Semiconductor Corporation – An Infineon Technologies Company
198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

PRODUCT CHANGE NOTIFICATION

PCN: PCN211204 **Date:** March 29, 2021

Subject: Qualification of Daewon Tray at ChipMOS Test and Finish Site for 44-Lead TSOP II Package Memory Products

To: TOKYO ELECTRON DEVICE
TELDEVICE
cy-inside@teldevice.co.jp

Change Type: Major

Description of Change:
Cypress announces the qualification of Daewon tray to be used for 44-Lead TSOP II package tested and finish processed at ChipMOS Technologies Inc., Taiwan. This tray is qualified and currently in use by Cypress and its other Test and Finish subcons.

This tray is compatible to industry standard as this tray is aligned to JEDEC requirements.

Items	Existing	New
Manufacturer	KOSTAT	DAEWON
Supplier Part Number	KS-8503	TR142050
Cypress Drawing Number	51-52029	001-94661
Tray Color	Black	Black
Temperature Rating	150°C	150°C
Number of Pockets / Units per Tray	135	135
Tray Length	315.0 ± 0.25 mm	315.0 ± 0.25 mm
Tray Width	135.9 ± 0.25 mm	135.9 ± 0.25 mm
Tray Stacking Height	6.35 ± 0.13 mm	6.35 ± 0.13 mm
1st Pocket X-Position	14.56 ± 0.13 mm	14.56 ± 0.13 mm
1st Pocket Y-Position	13.27 ± 0.13 mm	13.27 ± 0.13 mm
Pocket X-Pitch	20.42 ± 0.13 mm	20.42 ± 0.13 mm
Pocket Y-Pitch	13.67 ± 0.13 mm	13.67 ± 0.13 mm
Top Pocket Length	18.88 ± 0.25 mm	18.88 ± 0.08 mm
Top Pocket Width	11.96 ± 0.25 mm	11.87 ± 0.08 mm
Pocket Depth	1.91 ± 0.25 mm	1.91 ± 0.10 mm

Benefit of Change:
The qualification of the Daewon tray for 44-Lead TSOP II package at ChipMOS test and finish site will align ChipMOS to CML and the rest of the Cypress Subcon, which is also for tray standardization of this 44-Lead TSOP II package.

Part Numbers Affected: 64
See the attached ‘Affected Parts List’ file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PCN will include all changes outlined in this PCN.

Qualification Status:
This change has been qualified through a series of tests documented in the Qualification Test Plan QTP # 202106001. This qualification report can be found as an attachment to this PCN or by visiting www.cypress.com and typing the QTP number in the keyword search window.

Sample Status:
Qualification samples may not be built ahead of time for all part numbers affected by this change. Please review the attached ‘Affected Parts List’ file for a list of affected part numbers with their associated ChipMOS sample ordering part numbers. Samples are available now unless there is an indication that the sample ordering part numbers are subject to lead times. If you require qualification samples, please contact your local Cypress sales representative as soon as possible, preferably within 30 days of the date of this PCN, to place any sample orders.

Approximate Implementation Date:
Effective 90 days from the date of this notification or upon customer approval, whichever comes first, all shipments of Commercial, Industrial and Automotive non-PPAP part numbers in the attached file from ChipMOS will use Daewon trays.

For Automotive PPAP part numbers this change will be effective upon customer approval.

Anticipated Impact:
Products assembled with the Daewon tray are completely compatible with existing products from form, fit, functional, parametric and quality performance perspectives.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:
Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:
No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration